

# Schottky Diode

High Performance Schottky Diode  
 Low Loss and Soft Recovery  
 Common Cathode

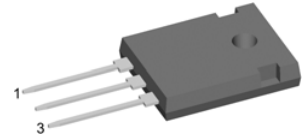
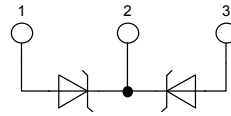
$$V_{RRM} = 150 \text{ V}$$

$$I_{FAV} = 2 \times 25 \text{ A}$$

$$V_F = 0.74 \text{ V}$$

Part number

**DSA 50 C 150 HB**



Backside: cathode

**Features / Advantages:**

- Very low  $V_f$
- Extremely low switching losses
- low  $I_{rm}$  values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

**Applications:**

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

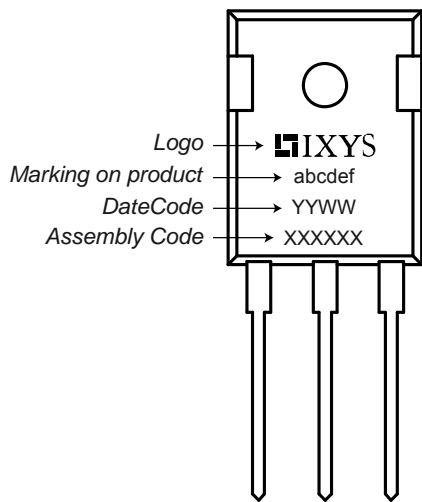
**Package:**

- Housing: TO-247
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

Symbol	Definition	Conditions	Ratings			Unit
			min.	typ.	max.	
$V_{RRM}$	max. repetitive reverse voltage				150	V
$I_R$	reverse current	$V_R = 150 \text{ V}$			0.5	$\mu\text{A}$
		$V_R = 150 \text{ V}$			5	mA
$V_F$	forward voltage	$I_F = 25 \text{ A}$			0.88	V
		$I_F = 50 \text{ A}$			1.02	V
		$I_F = 25 \text{ A}$			0.74	V
		$I_F = 50 \text{ A}$			0.90	V
$I_{FAV}$	average forward current	rectangular, $d = 0.5$			25	A
$V_{F0}$	threshold voltage	} for power loss calculation only			0.53	V
$r_F$	slope resistance				5.8	$\text{m}\Omega$
$R_{thJC}$	thermal resistance junction to case				0.95	K/W
$T_{VJ}$	virtual junction temperature		-55		175	$^{\circ}\text{C}$
$P_{tot}$	total power dissipation				160	W
$I_{FSM}$	max. forward surge current	$t = 10 \text{ ms}$ (50 Hz), sine			200	A
$C_J$	junction capacitance	$V_R = \text{tbd V}$ ; $f = 1 \text{ MHz}$		tbd		pF

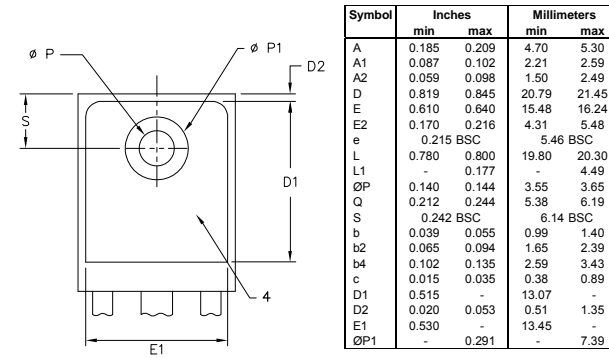
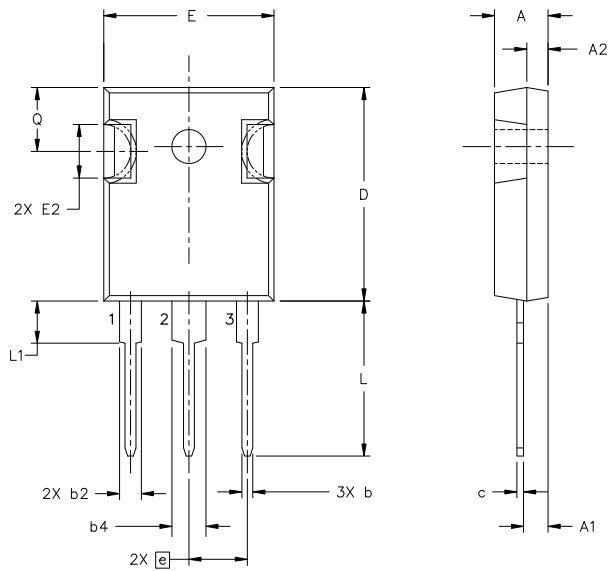
Symbol	Definition	Conditions	Ratings			Unit
			min.	typ.	max.	
$I_{RMS}$	RMS current	per pin <sup>1)</sup>			50	A
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W
$T_{stg}$	storage temperature		-55		150	°C
<b>Weight</b>				6		g
$M_D$	mounting torque		0.8		1.2	Nm
$F_C$	mounting force with clip		20		120	N

<sup>1)</sup>  $I_{RMS}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.  
 In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

**Product Marking**

**Part number**

D = Diode  
 S = Schottky Diode  
 A = low VF  
 50 = Current Rating [A]  
 150 = Reverse Voltage [V]  
 HB = TO-247AD (3)

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSA 50 C 150 HB	DSA50C150HB	Tube		

**Outlines TO-247**


Symbol	Inches		Millimeters	
	min	max	min	max
A	0.185	0.209	4.70	5.30
A1	0.087	0.102	2.21	2.59
A2	0.059	0.098	1.50	2.49
D	0.819	0.845	20.79	21.45
E	0.610	0.640	15.48	16.24
E2	0.170	0.216	4.31	5.48
e	0.215 BSC		5.46 BSC	
L	0.780	0.800	19.80	20.30
L1	-	0.177	-	4.49
$\varnothing P$	0.140	0.144	3.55	3.65
Q	0.212	0.244	5.38	6.19
S	0.242 BSC		6.14 BSC	
b	0.039	0.055	0.99	1.40
b2	0.065	0.094	1.65	2.39
b4	0.102	0.135	2.59	3.43
c	0.015	0.035	0.38	0.89
D1	0.515	-	13.07	-
D2	0.020	0.053	0.51	1.35
E1	0.530	-	13.45	-
$\varnothing P1$	-	0.291	-	7.39